


# MATERIAL DATA SHEET

Material #	CPDQR series(0402) (Halogen Free)	
Product Line	SOD-923F	
Date	2011/8/25	
Rev.	H	

## COMPONENT DETAILS

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)	Traces
1	FR-4 Board	Substrate/ Terminal	0.223	Copper	7440-50-8	43.00%	29.00%	
				Nickel	7440-02-0	3.68%		
				Gold	7440-57-5	0.10%		
				Continuous Filament Fiber Glass	65997-17-3	53.22%		
2	Wafer	Diode	0.029	Silicon	7440-21-3	97.948%	3.77%	
				Aluminum	7429-90-5	2.00%		
				Titanium	7440-32-6	0.001%		
				Silver	7440-22-4	0.001%		
				SiO2	14808-60-7	0.05%		
3	Al wire	Conductor	0.001	Aluminum	7429-90-5	99.00%	0.13%	
				Silicon	7440-21-3	1.00%		
4	Silver paste	Welding	0.005	Modified Epoxy Resin	29690-82-2	5~25%	0.65%	
				Silver	7440-22-4	76~85%		
				Imidazole	827-43-0	1~4%		
				Amide	461-58-5	1~4%		
5	Molding Compound	Outer	0.511	Silica	60676-86-0	70~90%	66.45%	
				Epoxy Resin	129915-35-1	6~16%		
				Phenolic Resin	26834-02-6	5~15%		
				Carbon Black	1333-86-4	0.1~1%		
		Total weight	0.769					